

N-Channel Enhancement-Mode Vertical DMOS FET

Features

- ► Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{iss} and fast switching speeds
- Excellent thermal stability
- Integral source-drain diode
- ► High input impedance and high gain

Applications

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

Ordering Information

Part Number	Package Option	Packing
VN4012L-G	TO-92	1000/Bag
VN4012L-G P002		
VN4012L-G P003		
VN4012L-G P005	TO-92	2000/Reel
VN4012L-G P013		
VN4012L-G P014		

⁻G denotes a lead (Pb)-free / RoHS compliant package.

Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV _{DSS}
Drain-to-gate voltage	BV _{DGS}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Typical Thermal Resistance

Package	$oldsymbol{ heta}_{j_{oldsymbol{a}}}$
TO-92	132°C/W

General Description

This enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Product Summary

BV_{DSS}/BV_{DGS} $R_{DS(ON)}$ (max)		V _{GS(TH)} (max)	l _{DSS} (min)		
400V	12Ω	1.8V	150mA		

Pin Configuration



Product Marking



YY = Year Sealed WW = Week Sealed _____ = "Green" Packaging

Package may or may not include the following marks: Si or

TO-92

Contact factory for Wafer / Die availablity

Devices in Wafer / Die form are lead (Pb)-free / RoHS compliant.

Thermal Characteristics

Package	l _D (continuous) [†]	l _D (pulsed)	Power Dissipation @T _c = 25°C	$\mathbf{I}_{DR}^{}t}$	I _{DRM}	
TO-92	160mA	650mA	1.0W	160mA	650mA	

Notes:

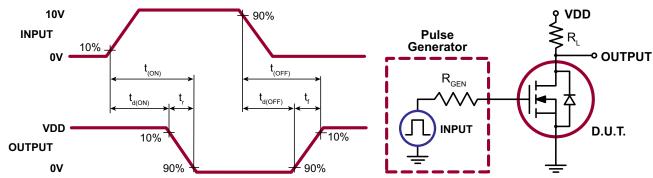
Electrical Characteristics (T_A = 25°C unless otherwise specified)

Sym	Parameter	Min	Тур	Max	Units	Conditions	
BV _{DSS}	Drain-to-source breakdown voltage	400	-	-	V	$V_{GS} = 0V, I_{D} = 100 \mu A$	
$V_{\rm GS(th)}$	Gate threshold voltage	0.6	-	1.8	V	$V_{GS} = V_{DS}$, $I_D = 1.0 \text{mA}$	
I _{GSS}	Gate body leakage	-	-	10	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
		-	-	1		$V_{GS} = 0V$, $V_{DS} = 0.8$ Max Rating	
I _{DSS}	Zero gate voltage drain current	-	-	100	μA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$, $T_{A} = 125$ °C	
I _{D(ON)}	On-state drain current	0.15	0.3	ı	Α	$V_{GS} = 4.5V, V_{DS} = 10V$	
D	Static drain-to-source on-state	-	9.5	12	Ω	$V_{GS} = 4.5V, I_{D} = 100mA$	
R _{DS(ON)}	resistance	-	17	30		$V_{GS} = 4.5V, I_{D} = 100mA, T_{A} = 125^{\circ}C$	
G_{FS}	Forward transductance	125	350	-	mmho	$V_{DS} = 15V, I_{D} = 100mA$	
C _{iss}	Input capacitance	-	-	110		V _{GS} = 0V,	
C _{oss}	Common source output capacitance	-	-	30	pF	$V_{DS} = 25V$,	
C _{RSS}	Reverse transfer capacitance	-	-	10		f = 1.0MHz	
t _r	Rise time	-	-	20			
t _{d(ON)}	Turn-on delay time	-	-	20		V _{DD} = 25V,	
t _f	Fall time	-	-	65	ns	$I_D = 100 \text{mA},$ $R_{GEN} = 25 \Omega$	
t _{d(OFF)}	Turn-off delay time	-	-	65		SL.	
V _{SD}	Diode forward voltage drop	-	-	1.2	V	V _{GS} = 0V, I _{SD} = 160mA	

Notes:

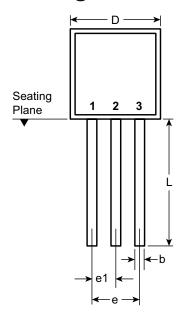
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

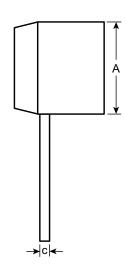
Switching Waveforms and Test Circuit



[†] I_D (continuous) is limited by max rated T_i .

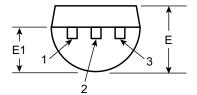
3-Lead TO-92 Package Outline (L)





Front View

Side View



Bottom View

Symbol		Α	b	С	D	E	E1	е	e1	L
Dimensions (inches)	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

Supertex inc. does not recommend the use of its products in life support applications, and will not knowingly sell them for use in such applications unless it receives an adequate "product liability indemnification insurance agreement." **Supertex inc.** does not assume responsibility for use of devices described, and limits its liability to the replacement of the devices determined defective due to workmanship. No responsibility is assumed for possible omissions and inaccuracies. Circuitry and specifications are subject to change without notice. For the latest product specifications refer to the **Supertex inc.** (website: http://www.supertex.com)

©2013 **Supertex Inc.** All rights reserved. Unauthorized use or reproduction is prohibited.



^{*} This dimension is not specified in the JEDEC drawing.

[†] This dimension differs from the JEDEC drawing.